WiLink™ 6.0 single-chip WLAN, Bluetooth® and FM solutions

Key features:

- Single-chip mobile WLAN, Bluetooth® and FM solution implemented in 65-nm CMOS process using TI’s DRP™ technology enables:
  - Reduced power consumption for extended talk and standby times
  - Bill of material reduction
  - Small form factor
- Proven carrier quality to enhance the user experience with range-extended mobile WLAN (802.11a/b/g/n), Bluetooth Specification 2.1 and FM functional cores
- Sophisticated ELP™ low-power technology and VoWLAN support with on-chip UMA and IMS acceleration for extended talk time and battery life
- Coexistence features enable simultaneous operation of each integrated function
- Certified Bluetooth Low Energy Release BT4.0 (WL1271/3L)

TI’s WiLink™ 6.0 mobile platform is a complete hardware and software offering comprising proven, carrier-quality mobile WLAN, Bluetooth® and FM cores integrated onto a single chip.

There are four solutions in the WiLink 6.0 product offering. The WL1271 supports 802.11b/g, while the WL1273 supports 802.11a/b/g/n. Both single-chip solutions support Bluetooth Specification 2.1 + EDR and FM transmit and receive. The WL1271/3L support Bluetooth Low Energy Specification 4.0.

The WiLink 6.0 single-chip solutions are manufactured in 65-nm CMOS process and use TI’s DRP™ technology to deliver low power, a small form factor and low cost requirements of handset manufacturers worldwide.

TI’s WiLink 6.0 platform is designed to work with OMAP™ 2 processors, OMAP 3 processors, the OMAP-Vox™ OMAPV1030 processor, and the “eCosto” OMAPV1035 solution to provide an optimized modem, applications processor and mWLAN/Bluetooth/FM solution for low- to mid-tier handsets.

The WiLink 6.0 solution includes TI’s proven, robust coexistence platform, which addresses system-wide interference issues, encompassing radio design, and hardware and software solutions. Coexistence expertise is becoming increasingly important as more radios are being added to the handset. TI leads
the market in coexistence solutions for Bluetooth and mWLAN with more than 30 handsets using TI’s coexistence platform.

The WiLink Software Development Kit (SDK) 6.x included with the WiLink 6.0 platform is optimized for mobile phone applications. This includes support for Linux®, Windows® WinCE™, and Symbian™ operating systems, as well as lab testing and manufacturing software. It is also partitioned to minimize host CPU loading and power consumption in mobile applications.

For more information

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